

Global Chiplet Advanced Packaging Technology Supply, Demand and Key Producers, 2026-2032

<https://marketpublishers.com/r/G9A9CD97C332EN.html>

Date: July 2026

Pages: 96

Price: US\$ 4,480.00 (Single User License)

ID: G9A9CD97C332EN

Abstracts

The global Chiplet Advanced Packaging Technology market size is expected to reach \$ 40845 million by 2032, rising at a market growth of 17.6% CAGR during the forecast period (2026-2032).

Chiplet Advanced Packaging Technology refers to a group of packaging technologies that integrate multiple modular semiconductor dies, known as chiplets, into a single package to create a system-level semiconductor device. Instead of implementing all functions on one large monolithic system-on-chip, the system is partitioned into smaller functional dies that can be designed, manufactured, tested and optimized separately.

Individual chiplets may perform computing, graphics processing, AI acceleration, I/O, SerDes, cache, memory control, RF, power-management or application-specific logic functions. These dies are connected through high-bandwidth die-to-die interconnects inside the package. Depending on the required interconnect density, the package may use an organic substrate, silicon interposer, organic interposer, embedded silicon bridge, redistribution layers, through-silicon vias, micro-bumps or copper-to-copper hybrid bonding. Chiplet-based packaging enables heterogeneous integration. Logic dies fabricated on advanced process nodes can be combined with I/O, analog or memory dies manufactured on more mature nodes. This architecture improves design reuse, provides greater system flexibility and can reduce the yield and cost risks associated with very large monolithic dies. Arm describes chiplets as silicon dies designed to operate as part of a larger packaged system, while the UCIe specification defines a standardized die-to-die interconnect framework intended to support a multi-vendor chiplet ecosystem.

This report studies the global Chiplet Advanced Packaging Technology demand, key

companies, and key regions.

This report is a detailed and comprehensive analysis of the world market for Chiplet Advanced Packaging Technology, and provides market size (US\$ million) and Year-over-Year (YoY) growth, considering 2025 as the base year. This report explores demand trends and competition, as well as details the characteristics of Chiplet Advanced Packaging Technology that contribute to its increasing demand across many markets.

Highlights and key features of the study

Global Chiplet Advanced Packaging Technology total market, 2021-2032, (USD Million)

Global Chiplet Advanced Packaging Technology total market by region & country, CAGR, 2021-2032, (USD Million)

U.S. VS China: Chiplet Advanced Packaging Technology total market, key domestic companies, and share, (USD Million)

Global Chiplet Advanced Packaging Technology revenue by player, revenue and market share 2021-2026, (USD Million)

Global Chiplet Advanced Packaging Technology total market by Type, CAGR, 2021-2032, (USD Million)

Global Chiplet Advanced Packaging Technology total market by Application, CAGR, 2021-2032, (USD Million)

This report profiles major players in the global Chiplet Advanced Packaging Technology market based on the following parameters - company overview, revenue, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include TSMC, Intel, Samsung Electronics, GlobalFoundries, SMIC, ASE Technology, Amkor Technology, JCET, Tongfu Microelectronics, Powertech Technology, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the world Chiplet Advanced Packaging Technology market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US\$

Millions), by player, by regions, by Type, and by Application. Data is given for the years 2021-2032 by year with 2025 as the base year, 2026 as the estimate year, and 2027-2032 as the forecast year.

Global Chiplet Advanced Packaging Technology Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Global Chiplet Advanced Packaging Technology Market, Segmentation by Type:

2.5D Advanced Packaging

3D Stacked Packaging

Fan-Out Packaging

Others

Global Chiplet Advanced Packaging Technology Market, Segmentation by Service Model:

Foundry Advanced Packaging

OSAT Advanced Packaging

IDM In-house Packaging

Global Chiplet Advanced Packaging Technology Market, Segmentation by Interconnect Technology:

TSV Packaging

Micro-bump Interconnect

Cu-Cu Hybrid Bonding

Others

Global Chiplet Advanced Packaging Technology Market, Segmentation by Chiplet Integration:

CPU + HBM Packaging

GPU + HBM Packaging

Logic + Memory Packaging

Others

Global Chiplet Advanced Packaging Technology Market, Segmentation by Application:

AI Accelerator

HPC Processor

Data Center Chip

Autonomous Driving Chip

Networking ASIC

Others

Companies Profiled:

TSMC

Intel

Samsung Electronics

GlobalFoundries

SMIC

ASE Technology

Amkor Technology

JCET

Tongfu Microelectronics

Powertech Technology

Key Questions Answered

1. How big is the global Chiplet Advanced Packaging Technology market?
2. What is the demand of the global Chiplet Advanced Packaging Technology market?
3. What is the year over year growth of the global Chiplet Advanced Packaging Technology market?
4. What is the total value of the global Chiplet Advanced Packaging Technology market?
5. Who are the Major Players in the global Chiplet Advanced Packaging Technology market?
6. What are the growth factors driving the market demand?

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